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**Supplier Acceptance**: true  
**Legal Declaration**: Standard

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<table>
<thead>
<tr>
<th>Mfr Item Number</th>
<th>Mfr Site</th>
<th>Date</th>
</tr>
</thead>
<tbody>
<tr>
<td>TSU102IQ2T</td>
<td>Z6HA</td>
<td>2013-07-04</td>
</tr>
</tbody>
</table>

<table>
<thead>
<tr>
<th>Amount</th>
<th>Unit type</th>
<th>ST ECOPACK Grade</th>
</tr>
</thead>
<tbody>
<tr>
<td>6.886</td>
<td>mg</td>
<td>ECOPACK® 2</td>
</tr>
</tbody>
</table>

### Manufacturing information

<table>
<thead>
<tr>
<th>J-STD-020 MSL Rating</th>
<th>Classification Temp</th>
<th>Nbr of Reflow Cycles</th>
<th>Comment</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>260</td>
<td>3</td>
<td></td>
</tr>
</tbody>
</table>

*bulk Solder Termination*

<table>
<thead>
<tr>
<th>Terminal Plating</th>
<th>Terminal Base Alloy</th>
<th>Comment</th>
</tr>
</thead>
<tbody>
<tr>
<td>Nickel/Palladium/Gold (Ni/Pd/Au)</td>
<td>Copper Alloy</td>
<td></td>
</tr>
</tbody>
</table>

*Not Applicable ; if coating is used or other bulk termination : add in comments*

<table>
<thead>
<tr>
<th>Package Designator</th>
<th>Size</th>
<th>Nbr of instances</th>
<th>Shape</th>
<th>Comment</th>
</tr>
</thead>
<tbody>
<tr>
<td>QFN</td>
<td>2.2x0.75</td>
<td>8</td>
<td>No lead</td>
<td>Package: MLPD/DFN 2x2x0.75 BL PITCH 0.5</td>
</tr>
<tr>
<td>Query</td>
<td>Response</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>----------------------------------------------------------------------</td>
<td>----------</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Product(s) meets EU RoHS requirement without any exemptions</td>
<td>true</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)</td>
<td>false</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Product(s) meets EU RoHS requirements by application of the selected exemption(s)</td>
<td>false</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Product(s) does not meet EU RoHS requirements and is not under exemptions</td>
<td>false</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Product(s) is obsolete, no information is available</td>
<td>false</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Product(s) is unknown, no information is available</td>
<td>false</td>
<td></td>
<td></td>
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</table>

<table>
<thead>
<tr>
<th>Exemption Id.</th>
<th>Description</th>
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**QueryList : REACH-19 December 2012**

<table>
<thead>
<tr>
<th>Query</th>
<th>Response</th>
</tr>
</thead>
<tbody>
<tr>
<td>The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH</td>
<td>true</td>
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</table>

<table>
<thead>
<tr>
<th>CategoryLevel_Name</th>
<th>CategoryLevel_Threshold</th>
<th>amount in product (mg)</th>
<th>Application</th>
<th>ppm in product</th>
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<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
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</tr>
<tr>
<td>Homogeneous Material</td>
<td>Material Group</td>
<td>I/class</td>
<td>UoM</td>
<td>Level</td>
</tr>
<tr>
<td>------------------------</td>
<td>-----------------------------</td>
<td>---------</td>
<td>-------</td>
<td>-------</td>
</tr>
<tr>
<td>Silicon die</td>
<td>Other inorganic materials</td>
<td>ng</td>
<td>SUPPLIER</td>
<td>Me</td>
</tr>
<tr>
<td>Leadframe</td>
<td>Copper and its alloy</td>
<td>1.562</td>
<td>mg</td>
<td>SUPPLIER</td>
</tr>
<tr>
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<td>Other inorganic materials</td>
<td>ng</td>
<td>SUPPLIER</td>
<td>Me</td>
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<td>Me</td>
</tr>
<tr>
<td>Die attach</td>
<td>Other organic materials</td>
<td>0.151</td>
<td>mg</td>
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<td>Bonding wire</td>
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